

FIG. 1A

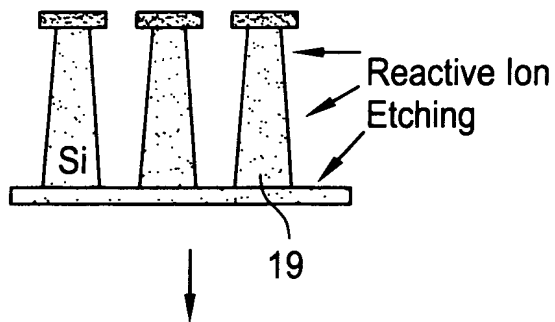


FIG. 1G

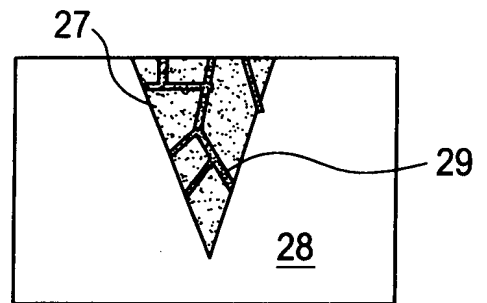


FIG. 1B

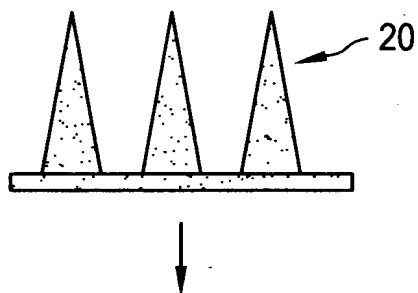


FIG. 1F

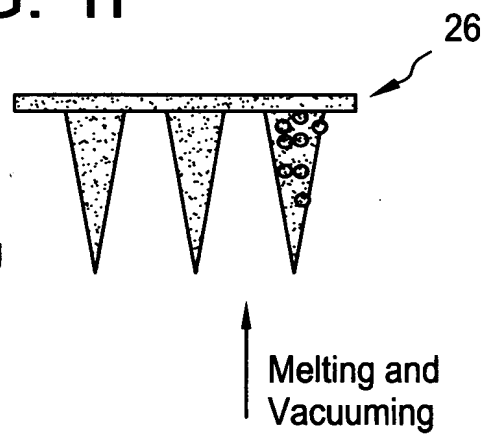


FIG. 1C

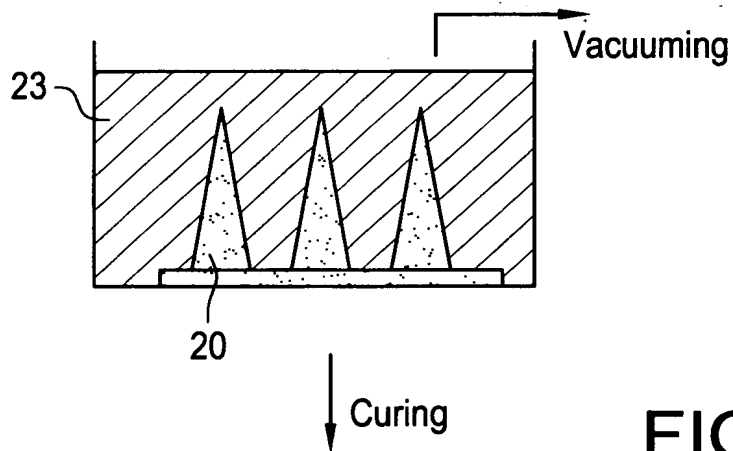


FIG. 1E

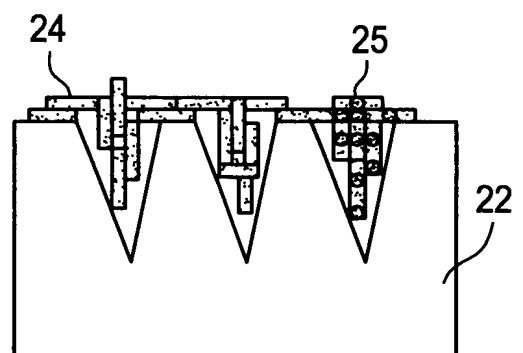


FIG. 1D



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FIG. 2A

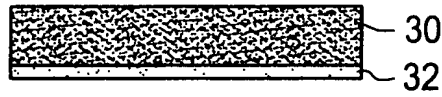


FIG. 2B

Aluminum deposition

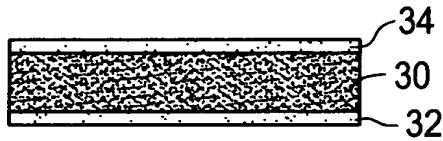


FIG. 2C

Photoresist Coating

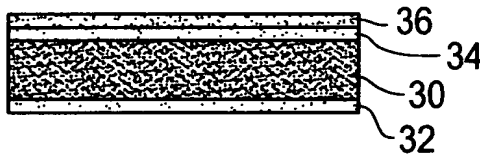


FIG. 2D

UV Exposure

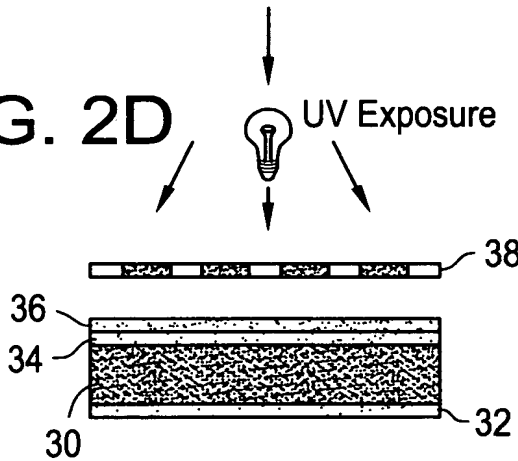


FIG. 2G

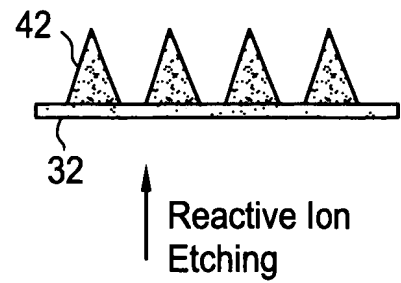


FIG. 2E

Developing

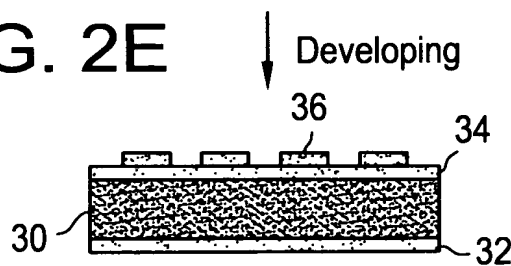


FIG. 2F

Al etching

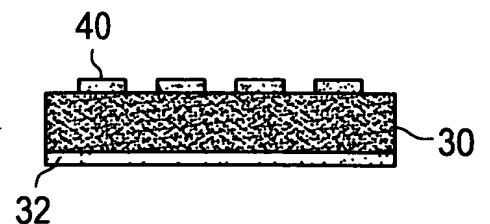
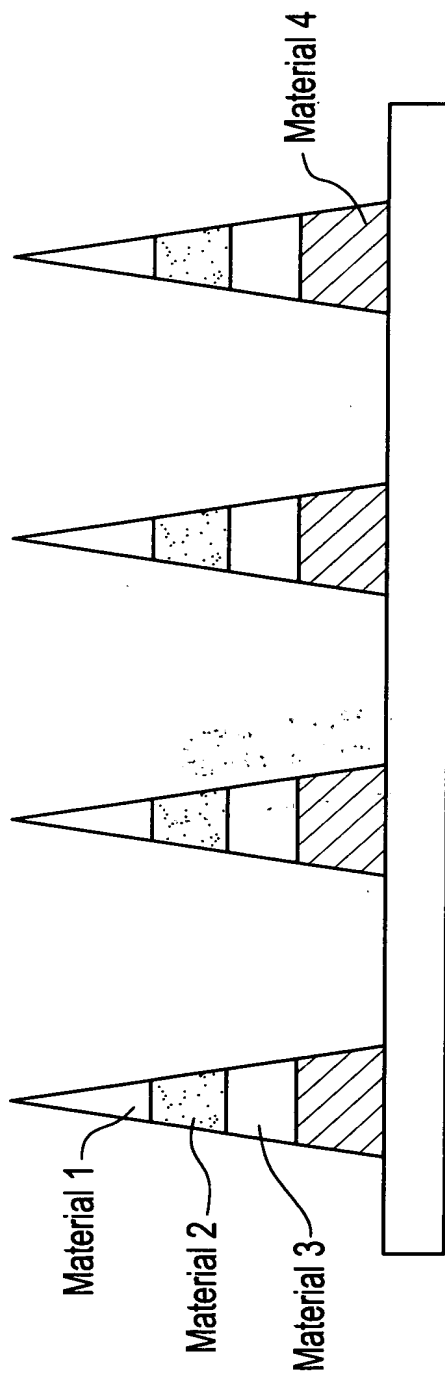
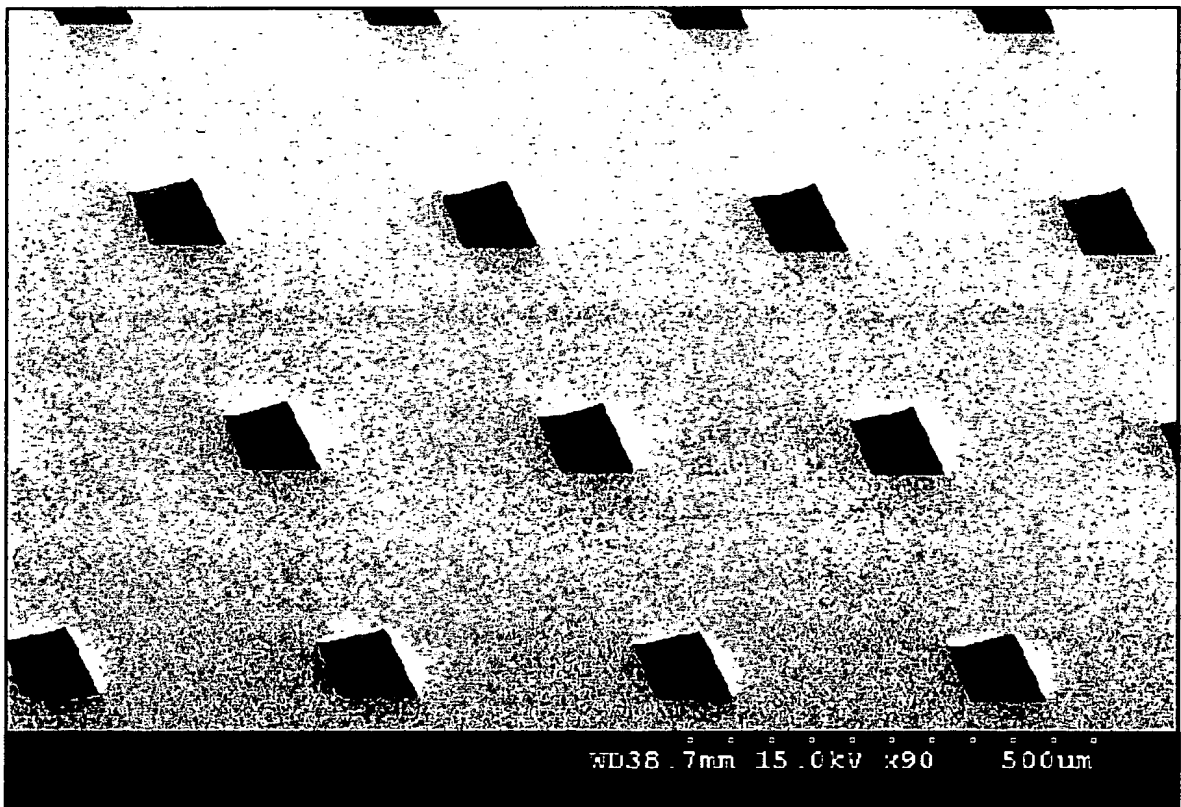


FIG. 3



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FIG. 4



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FIG. 5

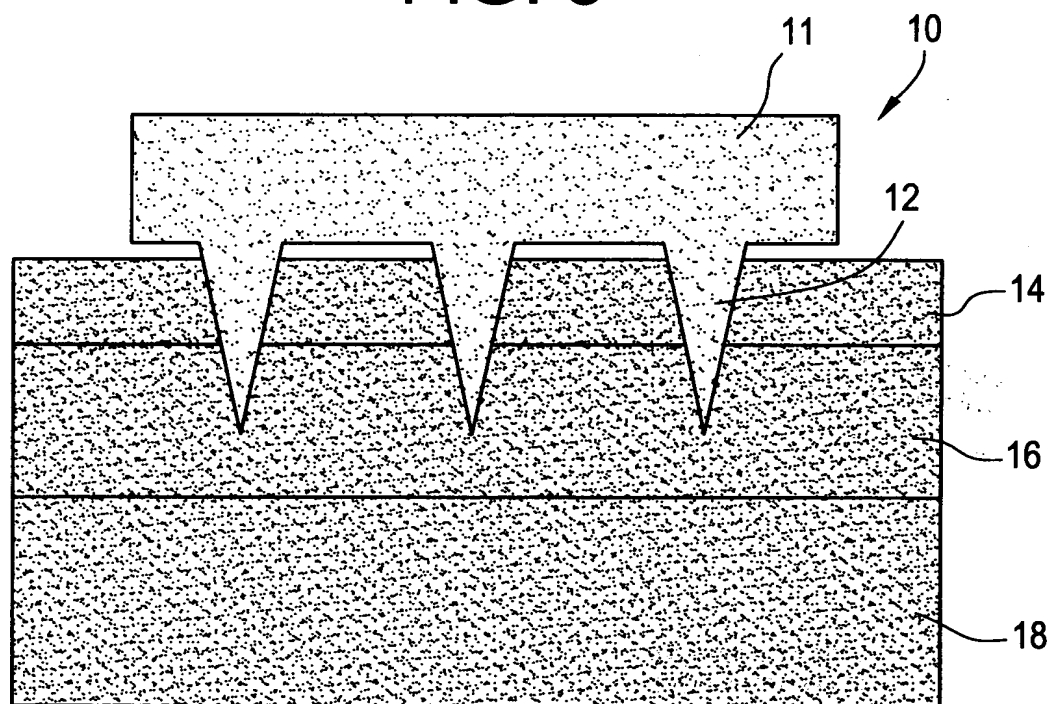


FIG. 6A

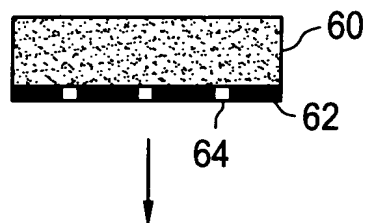


FIG. 6B

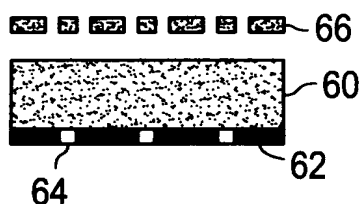


FIG. 6C



FIG. 6G



FIG. 6F

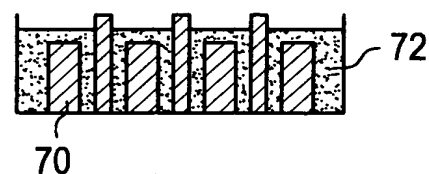


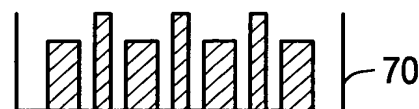
FIG. 6D

Developing of
Non-X-linked SU-8



FIG. 6E

Silicone mold
(Poly-dimethyl
siloxane)



Molding

FIG. 7A

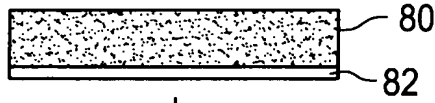


FIG. 7B

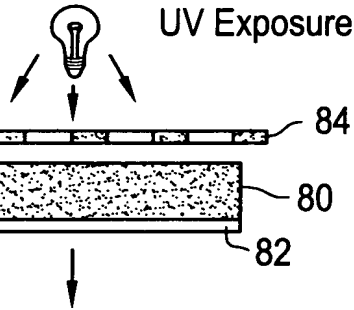


FIG. 7C

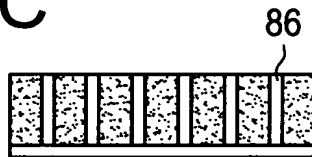


FIG. 7D

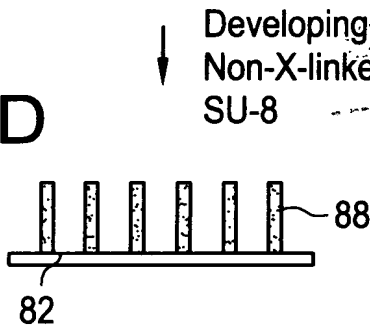


FIG. 7E

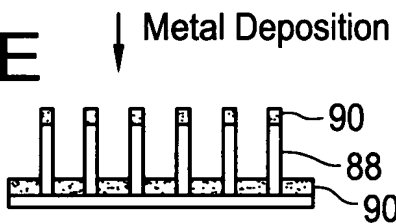


FIG. 7F

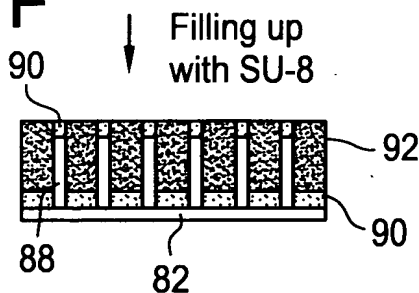


FIG. 7L

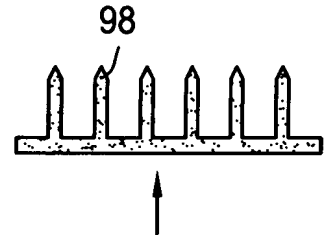


FIG. 7J

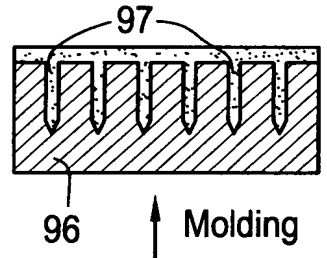


FIG. 7I

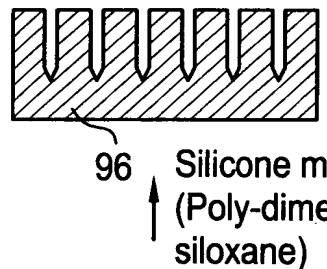


FIG. 7H

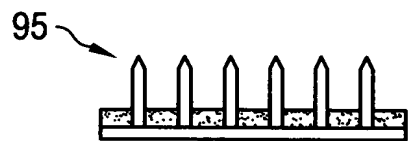


FIG. 7G

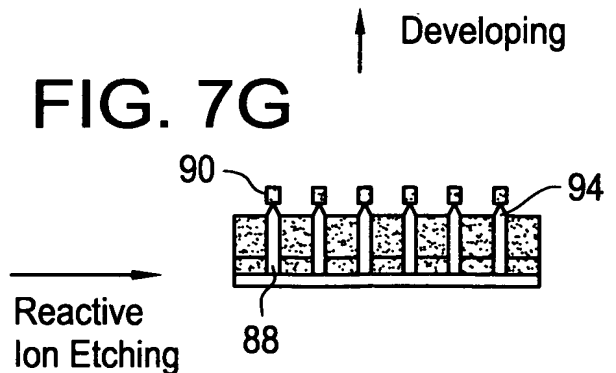


FIG. 8A

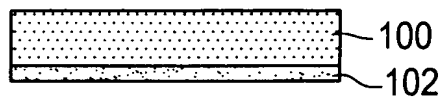
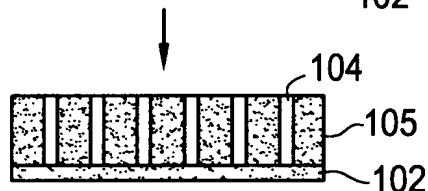
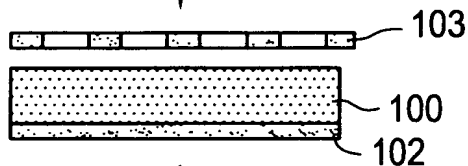


FIG. 8B



Developing



Sacrificial
polymer layer

FIG. 8C

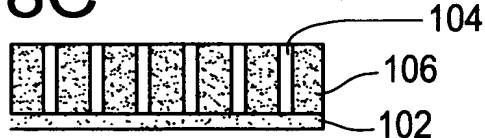


FIG. 8D

Metal Deposition

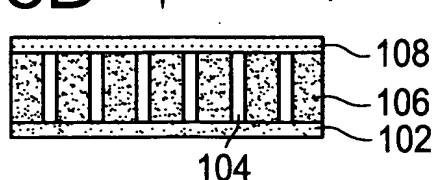


FIG. 8E

Photolithographic
work

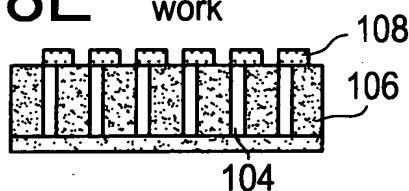
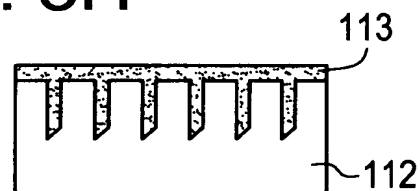


FIG. 8I



FIG. 8H

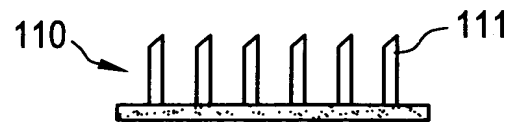


Molding



Silicone mold
(Poly-dimethyl
siloxane)

FIG. 8G



Removing
sacrificial
polymer layer

FIG. 8F

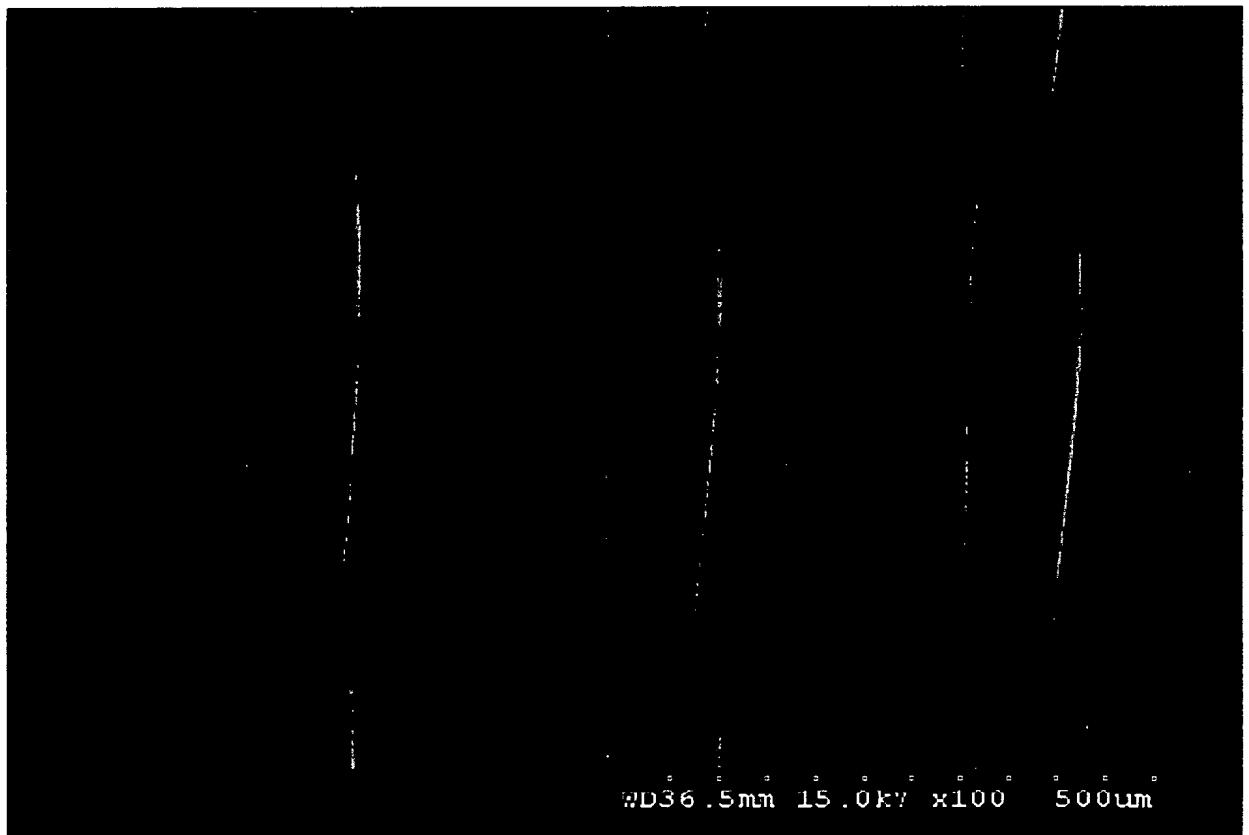
Reactive
Ion Etching



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FIG. 9



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FIG. 10A

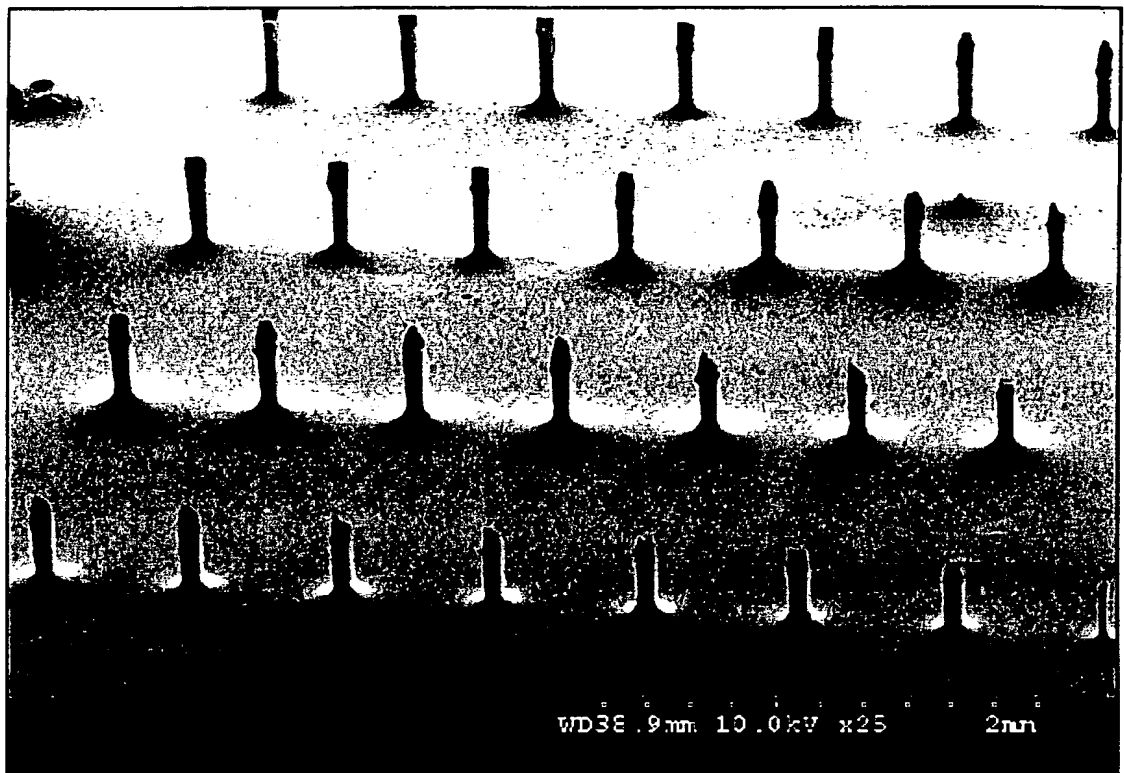
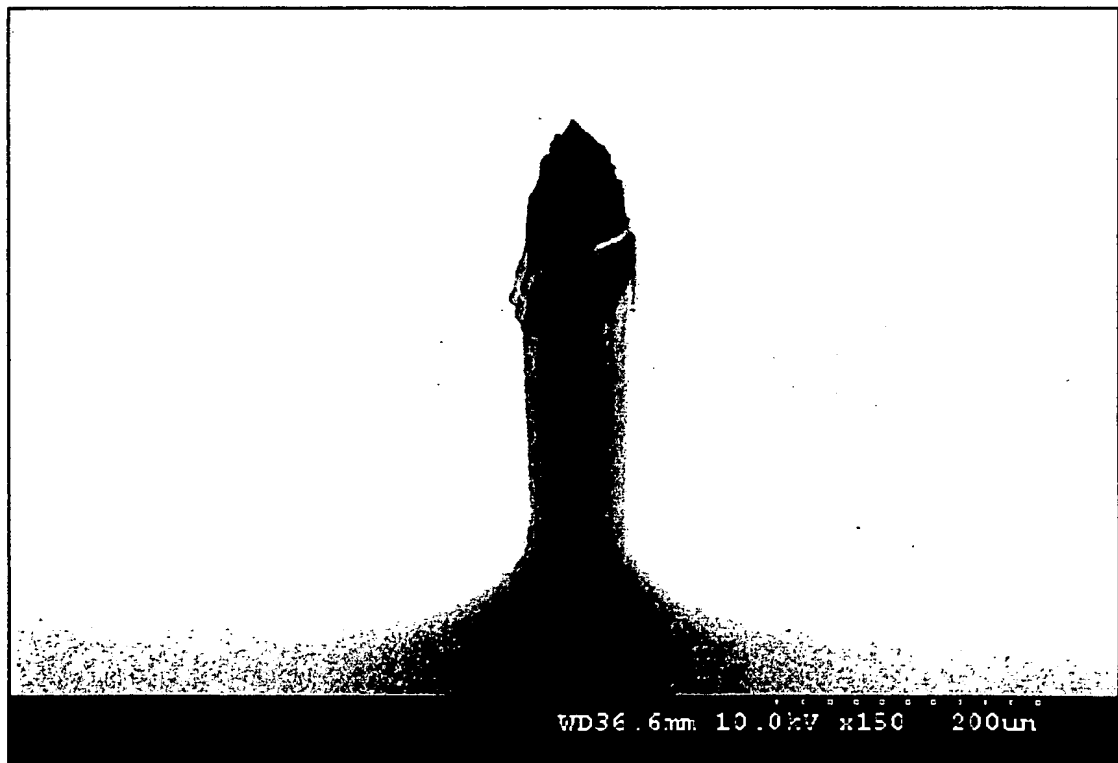


FIG. 10B



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FIG. 11A

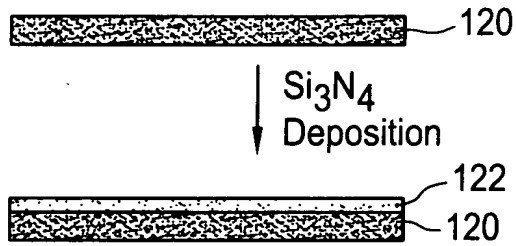


FIG. 11B

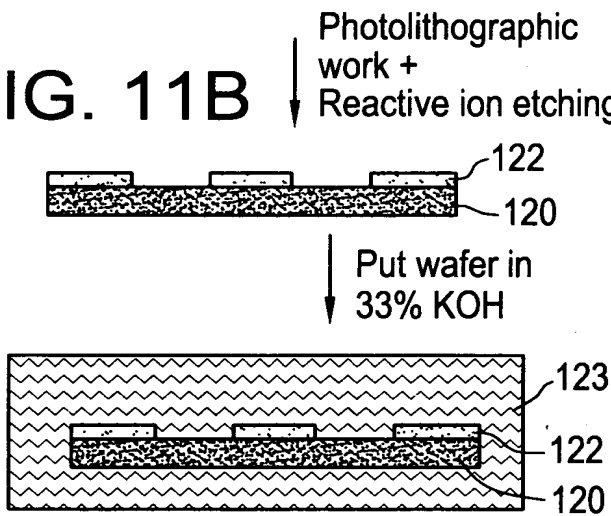


FIG. 11C

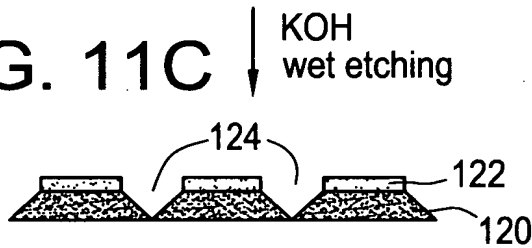


FIG. 11D

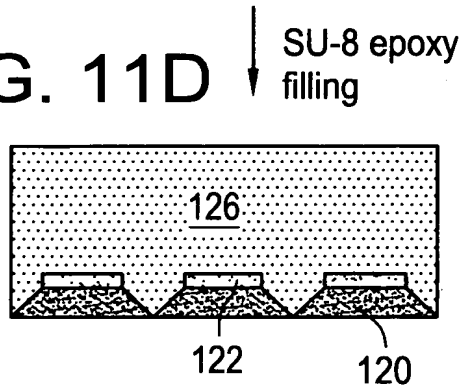


FIG. 11G

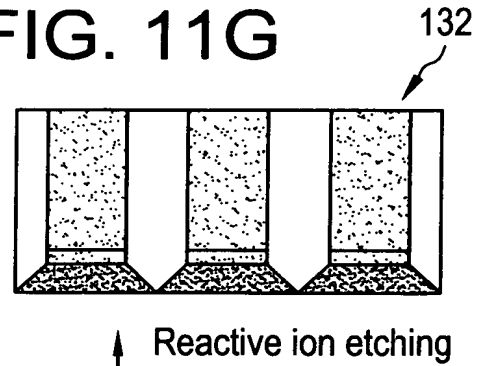


FIG. 11F

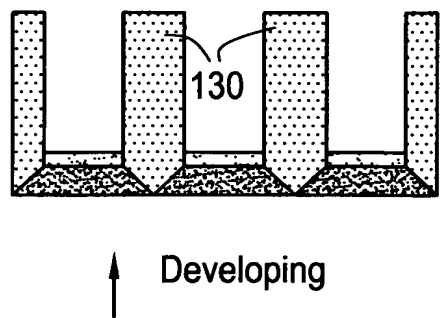
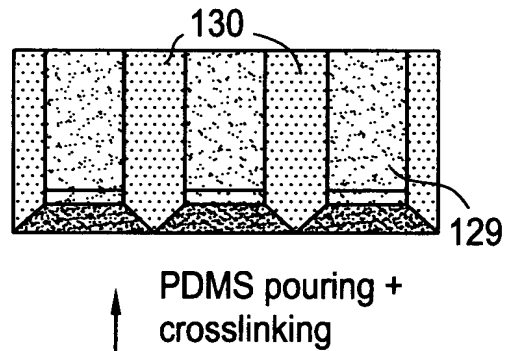
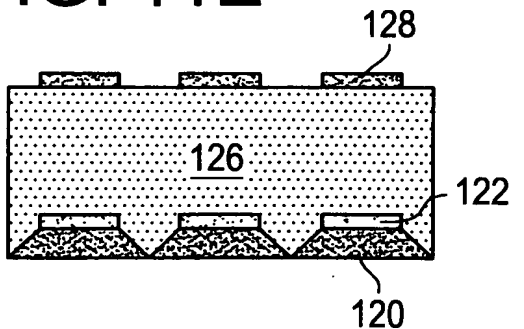
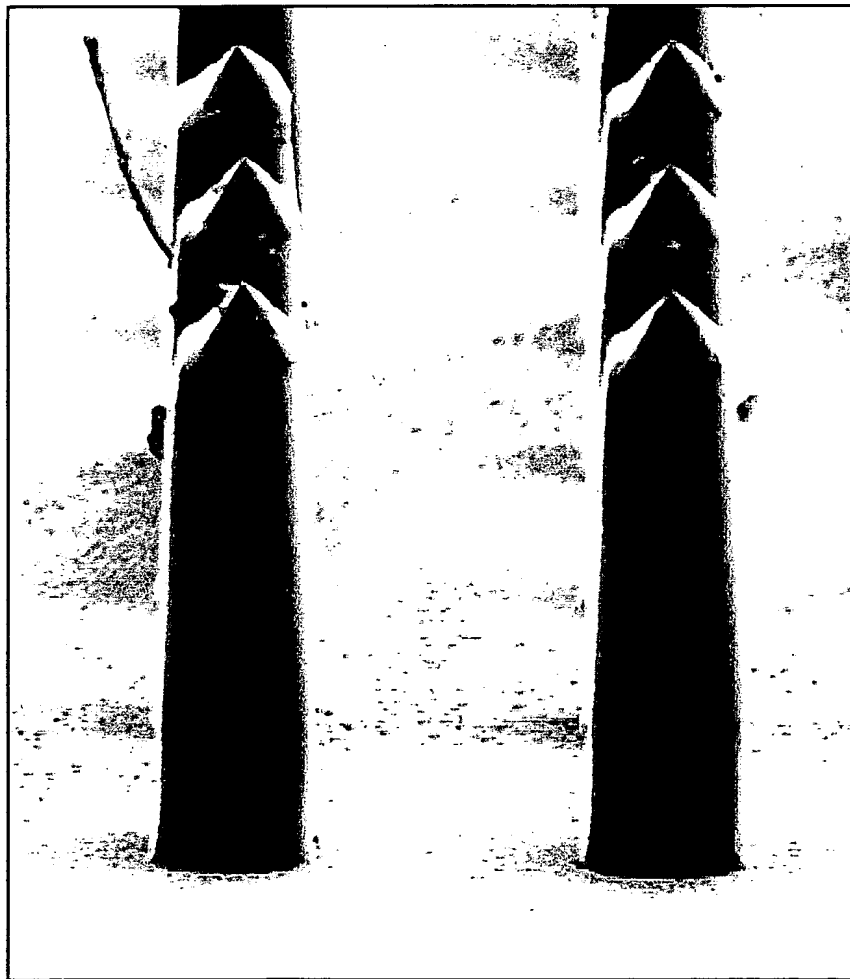


FIG. 11E



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FIG. 12



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